

Title (en)
PROCESS AND COMPOSITION FOR TREATING WOOD

Title (de)
VERFAHREN UND ZUSAMMENSETZUNG ZUR BEHANDLUNG VON HOLZ

Title (fr)
PROCEDE ET COMPOSITION DE TRAITEMENT DU BOIS

Publication
EP 1392452 A1 20040303 (EN)

Application
EP 02723715 A 20020329

Priority
• US 0210128 W 20020329
• US 28062001 P 20010330

Abstract (en)
[origin: WO02078865A1] A process for reducing the rate of deterioration of wood that includes contacting the wood with an aqueous alkaline colloidal silicon-containing salt composition that is supersaturated with a boron-containing salt. The contacting may be at ambient or elevated temperature and pressure. The composition is an aqueous colloidal silicon-containing salt that is supersaturated with a boron-containing salt and optionally includes an aluminum salt and a preservative. The composition is made by mixing the boron-containing salt with a colloidal, aqueous mixture of a silicon-containing salt and optionally adding the aluminum salt and the preservative. The process is performed under conditions that result in a supersaturated solution of the boron-containing salt. Wood treated with the composition appears to be resistant to insects, rot, UV deterioration, fire, and other environmental insults. The wood also appears to have increased strength.

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